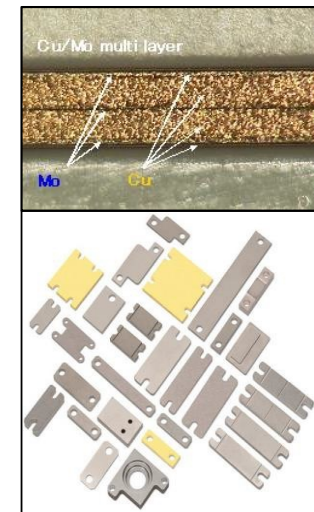




## Innovative Hermetic Solutions

### Cu-Mo Laminates, Super CMC

Material	Density [g/cm <sup>3</sup> ]	Cu	Mo	Cu	TTL Thickness	Coefficient of Thermal Expansion [10 <sup>-6</sup> /K]	Thermal Conductivity [W/mk] z	Thermal Conductivity [W/mk] xy
Cu-Mo-Cu	9.9	13%	74%	13%		5.7	170	200
Cu-Mo/Cu-Cu (CPC)	9.3					7.0 - 8.5	250	300
<b>S-CMC</b>	9.1					5.9-7.4	290+	340+
5 Mil	v5.9				5.6	5.9	205	265
	v7.5				5.0	7.4	290	340
7 Mil	v5.9				8.0	5.9	205	265
	v7.5				7.7	7.5	295	345
10 Mil	v5.9				11.4	5.9	205	265
	v7.5				10.0	7.4	290	340
20 Mil	v5.9				20.0	5.9	210	270
	v7.5				20.0	7.4	290	345
40 Mil	v5.9				39.4	5.9	205	265
	v7.5				39.4	7.4	290	340



### Heat Sinks - Various Materials

Material	Density [g/cm <sup>3</sup> ]	Thermal Conductivity [W/mk]		Thermal Expansion [10 <sup>-6</sup> /K]
		20°C	100°C	
AlN	3.3	180	150	4.5
Al <sub>2</sub> O <sub>3</sub>	3.8	25	17	6.7
BeO	2.9	285	180	7.6
Al-SiC*	2.7-3.2	80-200	-	6.8-12.0
Fe-Ni-Co	2.4	17	17	5.3
Si	2.3	151	-	4.8
GaAs	5.3	54	34	5.8
Mo	10.2	142	135	5.5
W	19.3	165	152	4.5
Cu	8.9	398	393	17.1

### Our Mission

To be your partner of choice, always trying to understand and deliver what will make you successful.

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